



**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V,$	-	-	1.0	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	$V_{GS}=10V, I_D=30A$	-	5.3	7.5	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V,$ $f=1.0MHz$	-	3136	-	pF
$C_{oss}$	Output Capacitance		-	286	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	257	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=30V, I_D=30A,$ $V_{GS}=10V$	-	90	-	nC
$Q_{gs}$	Gate-Source Charge		-	9	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	18	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=30V, I_D=30A,$ $R_G=1.8\Omega, V_{GS}=10V$	-	9	-	ns
$t_r$	Turn-on Rise Time		-	7	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	40	-	ns
$t_f$	Turn-off Fall Time		-	15	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	90	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	320	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=30A$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=30A, di/dt=100A/\mu s$	-	33	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	46	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=30V$ ,  $V_G=10V$ ,  $L=0.5mH$ ,  $R_g=25\Omega$ ,  $I_{AS}=26A$

3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

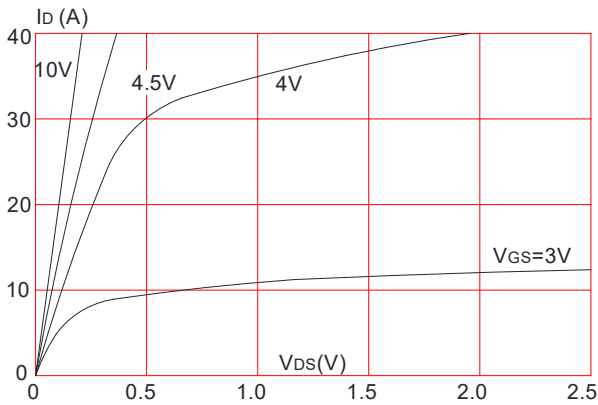


Figure 2: Typical Transfer Characteristics

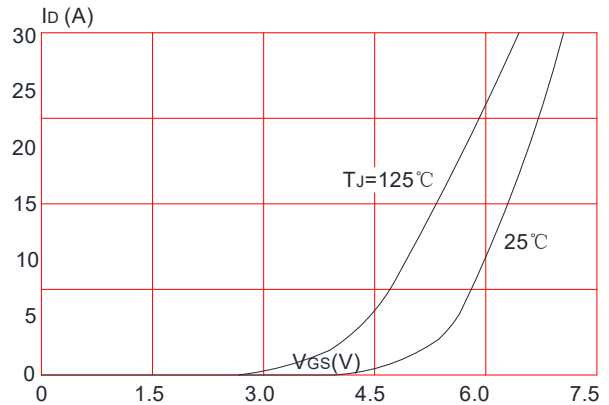


Figure 3: On-resistance vs. Drain Current

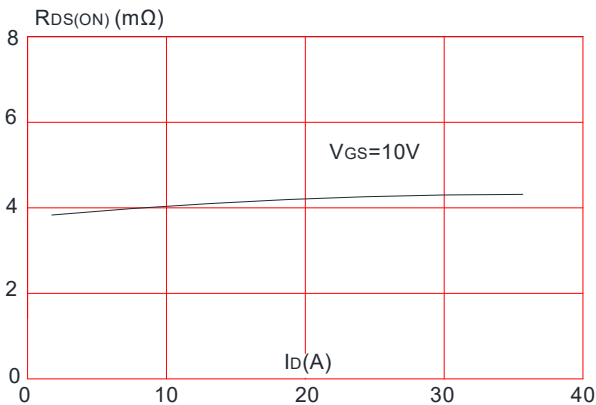


Figure 4: Body Diode Characteristics

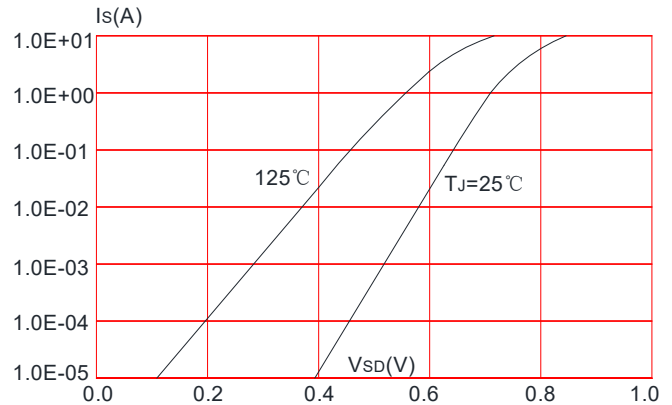


Figure 5: Gate Charge Characteristics

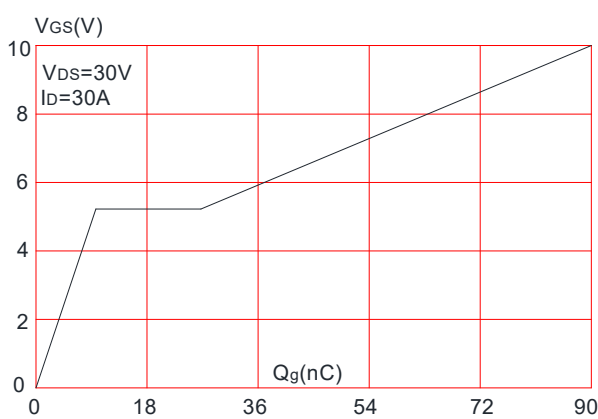
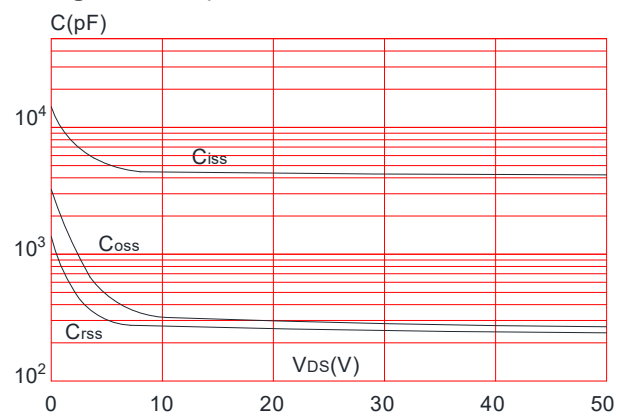
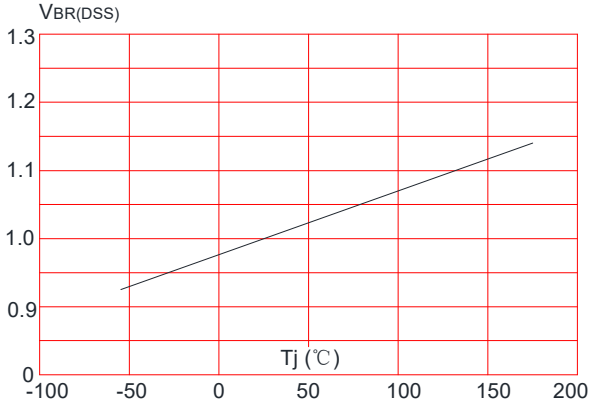


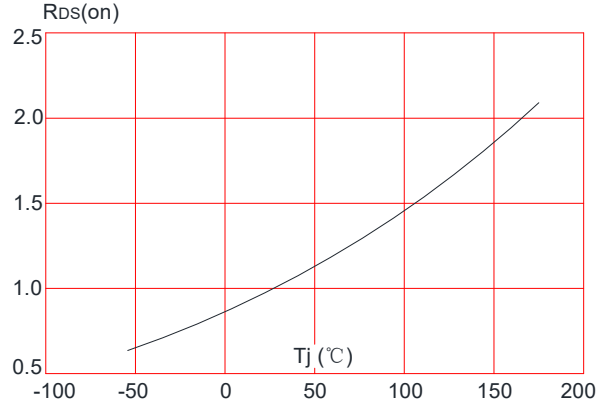
Figure 6: Capacitance Characteristics



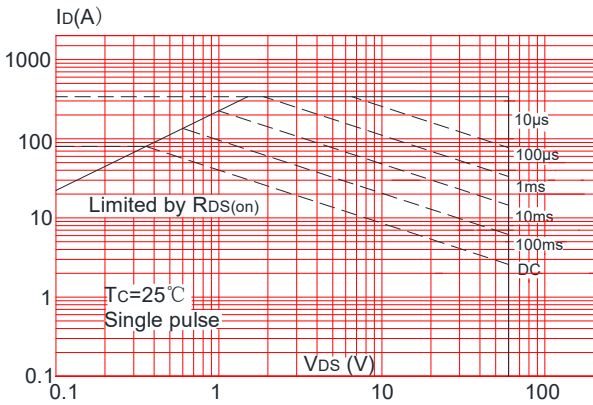
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



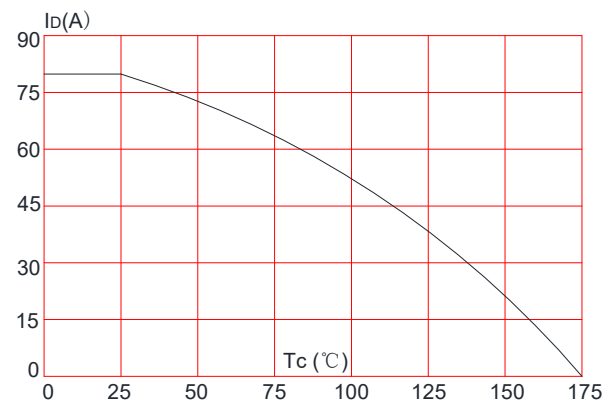
**Figure 8:** Normalized on Resistance vs. Junction Temperature



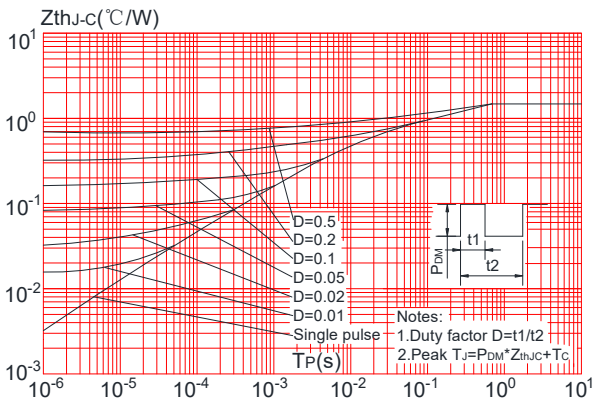
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



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